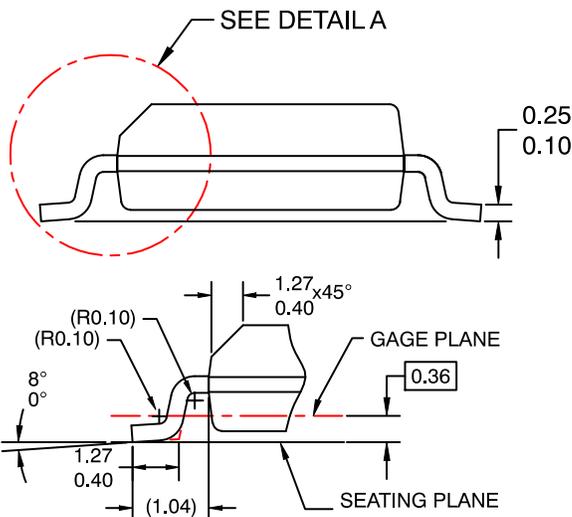
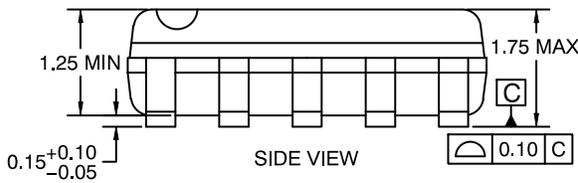
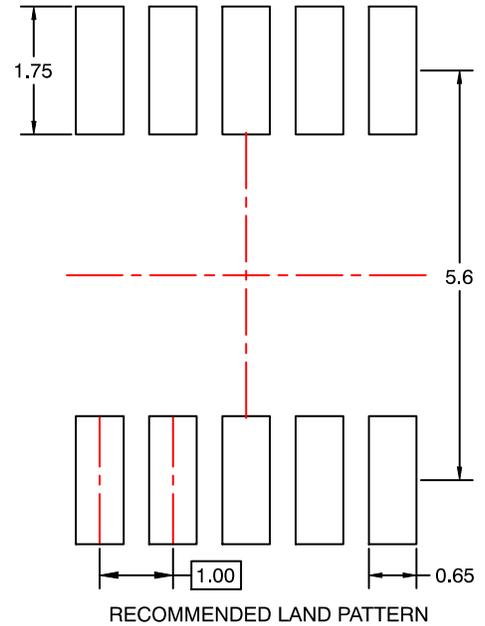
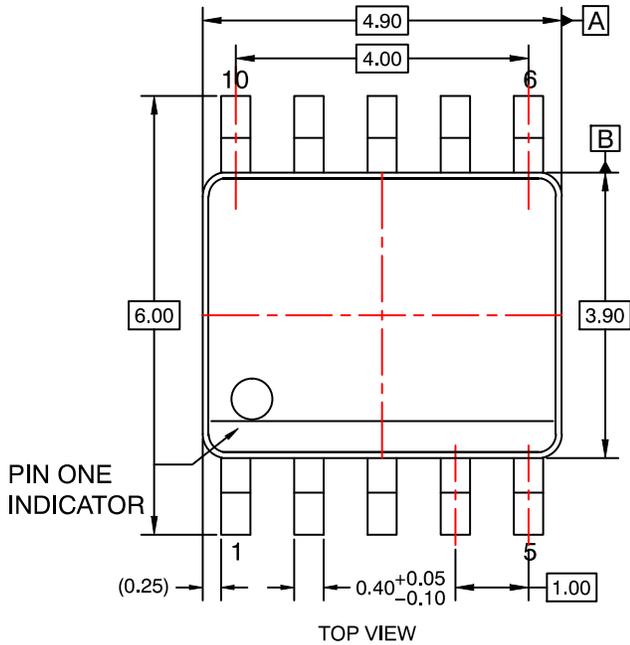


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

SOIC10
CASE 751EE
ISSUE O

DATE 30 SEP 2016



NOTES:

- A. THIS PACKAGE DOES NOT FULLY CONFORM TO JEDEC REGISTRATION, MS-012.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. DIMENSIONS DO NOT INCLUDE MOLD FLASH AND BURRS.
- E. LAND PATTERN STANDARD : SOIC127P600X175.10M

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SOIC10	PAGE 1 OF 2

